



Image Sensors and Companion Chips

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Message from the Guest Editor

CMOS image sensors are highly integrated optoelectronic chips which convert optical information into digital information that is easy to process and store. With the development of 3D integration and packaging technology, multiple chips can be integrated into one chip to form more compact imaging systems.

This Special Issue encourages researchers to present their theories, techniques, circuits, and systems of CMOS chips for image sensing and companion chips. The scope of this Special Issue focuses on, but is not limited to:

- CMOS image sensor modeling;
- High-performance active pixels;
- Low-noise readout circuits;
- High-speed imaging techniques;
- Dynamic range extension technology;
- Low-light imaging;
- High-resolution imaging;
- 3D imaging;
- Dynamic vision sensors;
- Spike-based image sensors;
- Sensory and computational integration;
- Image signal processing;
- Single photon counting technique;
- Image sensor interfaces.





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Message from the Editor-in-Chief

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